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In the Claims:

Please add the following new claims.

106. (New) The method of claim 42, further comprising nipping said continuous film and said substrate between a first roller and a second roller,
107. (New) The method of claim 106, wherein said contacting and said nipping occur substantially simultaneously.
108. (New) The method of claim 42, wherein said substrate comprises a polymeric film.
109. (New) The method of claim 42, wherein said substrate comprises foil.
110. (New) The method of claim 42, wherein said substrate comprises metallized polymeric film.
111. (New) The method of claim 42, wherein the substrate of said coated substrate is a first substrate, said method further comprising contacting the coating of said coated substrate with a second substrate.
112. (New) The method of claim 111, wherein said second substrate comprises a polymeric film.
113. (New) The method of claim 111, wherein said second substrate comprises foil.
114. (New) The method of claim 111, wherein said second substrate comprises metallized polymeric film.

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115. (New) The method of claim 111, wherein said second substrate comprises paper.

116. (New) The method of claim 112, wherein said first substrate comprises a polymeric film.

117. (New) The method of claim 113, wherein said first substrate comprises foil.

118. (New) The method of claim 113, wherein said first substrate comprises polymeric film.

119. (New) The method of claim 114, wherein said first substrate comprises metallized polymeric film.

120. (New) The method of claim 42, wherein said hot melt adhesive has a complex viscosity of less than about 500 poise at 1000 radians/sec at the coating temperature.

121. (New) The method of claim 120, wherein said hot melt adhesive has a complex viscosity of less than about 1000 poise at 1 radians/sec at the coating temperature

122. (New) The method of claim 42, wherein the adhesive composition is released from the coating device at a temperature less than about 177°C.

123. (New) The method of claim 42, wherein the adhesive composition is released from the coating device at a temperature less than about 160°C.

124. (New) The method of claim 42, wherein the adhesive composition is released from the coating device at a temperature less than about 125°C.

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125. (New) The method of claim 42, wherein the adhesive composition is released from the coating device at a temperature less than about 110°C.

126. (New) The method of claim 42, wherein the distance between the coating device and the substrate is greater than 20 mm.

127. (New) The method of claim 42, wherein the coating device is a slot nozzle.